PulseForge® Lift-Off™:

Low Cost, High Throughput Non-Laser Lift-Off of Polyimide and Other Polymers

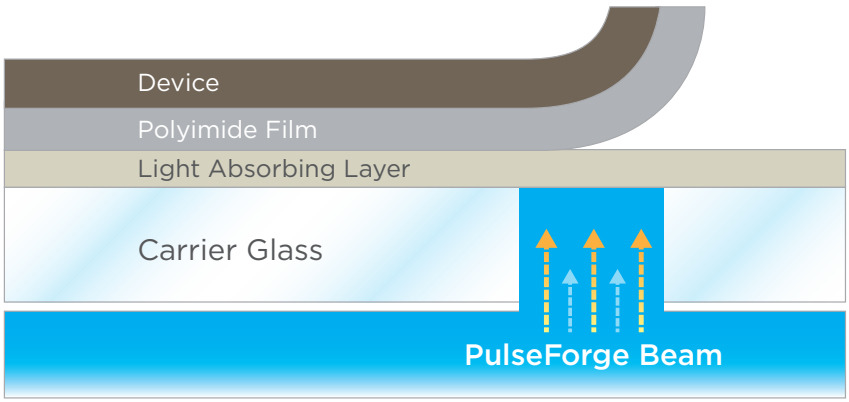
NovaCentrix has developed a reliable non-laser technology to rapidly and economically lift-off polymeric films carrying thin film electronic structures from rigid glass substrates. PulseForge® Lift-Off™ is suitable for OLED, TFT-based displays and photovoltaic applications.

CAPABILITIES

- Ultrafast heating of the interface leads to decomposition of the polymeric surface and leads to release of the free-standing polymeric film
- Glass carrier substrates are upgraded with additional light absorbers to enhance interface heating and prevent light exposure within the device stack
- Expandable to meet Generation 5.5 substrate size needs
- High absorption and high thermal tolerance substrate is required for fidelity of processing
- PulseForge® Lift-Off™ process is not feasible on crystalline silicon

HOW IT IS BETTER

- Processing rate of up to 5m/min
- Equipment costs are a fraction of laser-based lift-off processing tools
- Removal of the device stack without illuminating the active layer
- Enhanced tolerance for imperfections within the polyimide coating



NovaCentrix
400 Parker Drive
Suite 1110
Austin, Texas 78728

T: 512-491-9500
F: 512-491-0002

info@novacentrix.com
www.novacentrix.com